
October 21 (Wed.), 2026

[Oral 06] CMP for Advanced Packaging / 3D Integration (II)

09:45-11:10

International Conference Hall (B1F)

● Session Chair: Takashi Watanabe (KIOXIA Corp., Japan)

09:45-10:10

[Oral 06-1]

[Invited] Considerations for Implementing CMP in Panel-Level Packaging

Haedo Jeong, Heondeok Seo, Minjong Yuh, and Eunho Lee (G&P Tech., Korea)

10:10-10:30

[Oral 06-2]

Die-to-Wafer CMP: Overcoming Millimetric Planarization Challenges Driven by Die Density

Julian Sturm (Univ. Grenoble Alpes, France), Valentin Callier (EBARA Precision Machinery Europe GmbH – Branch Office France, France), Clément Castan (Univ. Grenoble Alpes, France), Lucie Safourcade (EBARA Precision Machinery Europe GmbH – Branch Office Fr

10:30-10:50

[Oral 06-3]

Effect of Slurry pH and Chelating Agent on Surface Roughness and Removal Rate of AlN in SiO₂ Slurry CMP

Bo-Hyeok Cho, Jae-Ik Lee, Seung-Mahn Lee, and Jae-Dong Lee (KCTech, Korea)

10:50-11:10

[Oral 06-4]

Polishing Material Impact on Silicon Wafer Processing

Hui Wang (Zhonghuan Advanced Company, China)